

## CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME

### ABSTRACT

A method of making a circuitized substrate such as a laminate chip carrier in which a polymer, e.g., Teflon, is used as a dielectric layer and a promotion adhesion layer of a polymer is used to securely adhere a conductive layer thereto which is deposited by plating. The resulting product is thus able to provide extremely narrow conductive circuitry for subsequent connections, e.g., to a semiconductor chip. Electroless plating is the preferred plating method with the dielectric immersed in a solution of conductive monomers, e.g., pyrrole monomer, the solution also possibly containing a seed material such as palladium-tin.